



Material Content Data Sheet



Sales Product Name	TLF4277EL			Issued	24. January 2018			
MA#	MA000724686							
Package	PG-SSOP-14-2			Weight*	83.82 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.604	5.49	5.49	54926	54926
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		411	
	non noble metal	iron	7439-89-6	0.689	0.82		8220	
wire	non noble metal	copper	7440-50-8	27.978	33.38	34.25	333770	342504
	noble metal	gold	7440-57-5	0.107	0.13	0.13	1277	1277
	encapsulation	organic material	carbon black	1333-86-4	0.094	0.11		1116
encapsulation	plastics	epoxy resin	-	4.301	5.13		51313	
	inorganic material	silicondioxide	60676-86-0	42.358	50.54	55.78	505323	557752
leadfinish	non noble metal	tin	7440-31-5	0.988	1.18	1.18	11791	11791
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9157	9157
glue	plastics	epoxy resin	-	0.473	0.56		5648	
	noble metal	silver	7440-22-4	1.420	1.69	2.25	16945	22593
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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